# 2SC3932

## Silicon NPN epitaxial planar type

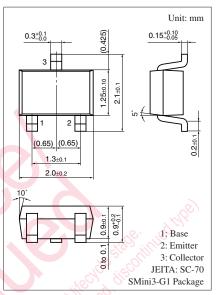
For high-frequency amplification/oscillation/mixing

#### ■ Features

- High transition frequency f<sub>T</sub>
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

### ■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter                             | Symbol           | Rating      | Unit |  |
|---------------------------------------|------------------|-------------|------|--|
| Collector-base voltage (Emitter open) | V <sub>CBO</sub> | 30          | V    |  |
| Collector-emitter voltage (Base open) | V <sub>CEO</sub> | 20          | V    |  |
| Emitter-base voltage (Collector open) | V <sub>EBO</sub> | 3           | V    |  |
| Collector current                     | $I_C$            | 50          | mA   |  |
| Collector power dissipation           | P <sub>C</sub>   | 150         | mW   |  |
| Junction temperature                  | T <sub>j</sub>   | 150         | °C   |  |
| Storage temperature                   | T <sub>stg</sub> | -55 to +150 | °C   |  |



Marking Symbol: R

### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

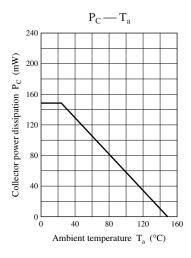
| Parameter  | Symbol           | Conditions   | Min | Тур | Max  | Unit |
|--|------------------|--|-----|-----|------|------|
| Collector-base voltage (Emitter open)            | V <sub>CBO</sub> | $I_C = 100 \mu\text{A},  I_E = 0$                                  | 30  |     |      | V    |
| Emitter-base voltage (Collector open)            | $V_{EBO}$        | $I_E = 10 \ \mu A, I_C = 0$  | 3   |     |      | V    |
| Base-emitter voltage                             | $V_{BE}$         | $V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}$                       |     | 720 |      | mV   |
| Forward current transfer ratio                   | h <sub>FE</sub>  | $V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}$                       | 25  |     | 250  | _    |
| Transition frequency *                           | $f_T$            | $V_{CB} = 10 \text{ V}, I_E = -15 \text{ mA}, f = 200 \text{ MHz}$ | 800 |     | 1600 | MHz  |
| Reverse transfer capacitance<br>(Common base)    | Crb              | $V_{CE} = 6 \text{ V}, I_{C} = 0, f = 1 \text{ MHz}$               |     | 0.8 |      | pF   |
| Reverse transfer capacitance<br>(Common emitter) | $C_{re}$         | $V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 10.7 \text{ MHz}$ |     | 1.0 | 1.5  | pF   |
| Power gain                                       | $G_{P}$          | $V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 200 \text{ MHz}$  |     | 20  |      | dB   |

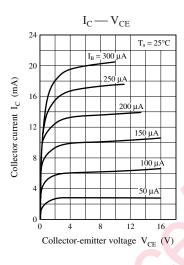
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

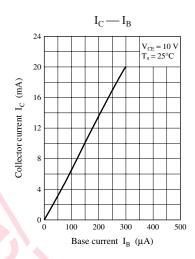
#### 2. \*: Rank classification

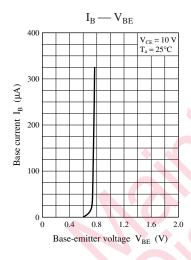
| Rank           | Т           | S            | No-rank     |
|----------------|-------------|--------------|-------------|
| $f_T$          | 800 to 1400 | 1000 to 1600 | 800 to 1600 |
| Marking symbol | RT          | RS           | R           |

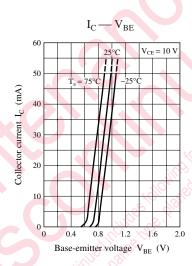
Product of no-rank is not classified and have no indication for rank.

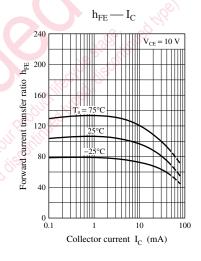


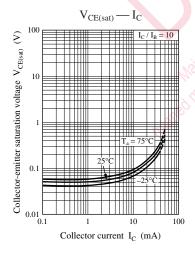


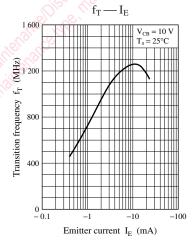


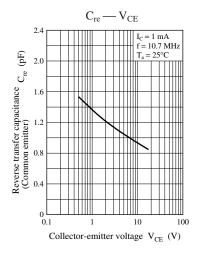


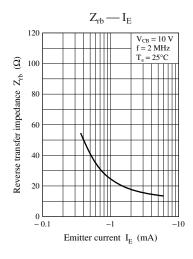


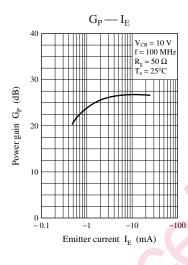


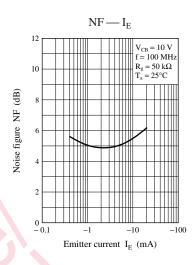


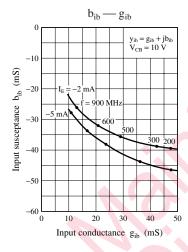


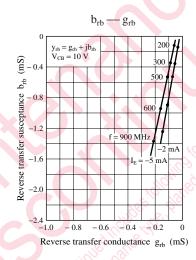


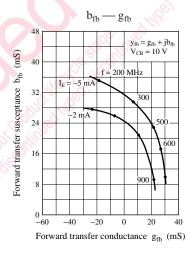


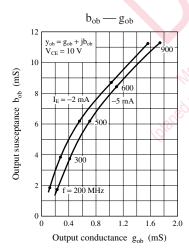












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